

# PATENT APPLICATION

In re the Application of

Attn: OIPE

Shigehiro NISHINO et al.

Group Art Unit: 1722

Application No.:

10/520,141

Docket No.:

122261

Filed: September 1, 2005

For:

LARGE-DIAMETER SIC WAFER AND MANUFACTURING METHOD THEREOF

THE UNITED STATES PATENT AND TRADEMARK OFFICE

## REQUEST FOR CORRECTION OF PALM RECORDS

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted,

James A. Oliff

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JAO:KKV/aal

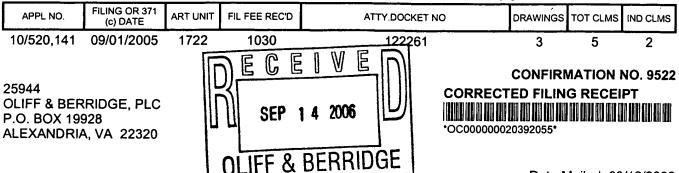
Date: October 3, 2006

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Date Mailed: 09/12/2006

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## Applicant(s)

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## **Assignment For Published Patent Application**

MITSUI ENGINEERING & SHIPBUILDING CO., LTD, TOKYO, JAPAN

Power of Attorney: The patent practitioners associated with Customer Number 25944.

# Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP03/08312 06/30/2003

#### Foreign Applications

JAPAN 2002-202953 07/11/2002

If Required, Foreign Filing License Granted: 09/12/2006

The country code and number of your priority application, to be used for filing abroad under the Paris Convention, is **US10/520,141** 

Projected Publication Date: Not Applicable

Non-Publication Request: No

**Early Publication Request: No** 

Concetion also on title

Title

Large-Diameter Wafer and Manufacturing Method Thereof

**Preliminary Class** 

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